

# *WoDiM 2010 Final Call for Abstracts*

*16<sup>th</sup> Workshop on Dielectrics in Microelectronics  
June 28 – 30, 2010, Bratislava, Slovakia  
AVS Sponsored Topical Conference*



## *Scope of the Workshop*

New challenges offered by the application of dielectric materials in microelectronics will be discussed during the 16th Workshop on Dielectric Materials, WoDiM 2010. The goal of the WoDiM 2010 conference is to create a stimulating international platform for application-oriented scientists to exchange ideas and the latest experimental results covering the physics, technology and characterisation of dielectric materials in silicon integrated circuits.

## *Topics*

### **Emerging dielectric materials, technologies and new device approaches**

Theory of dielectric materials, interface science of dielectrics in contact with semiconductors & metals  
Advanced technologies for thin dielectric film growth (ALD, MOCVD, PLD, MBE,...)  
Characterisation of dielectrics with high sensitivity & spatial resolution, characterisation at nano-scale  
Multiferroics, 2-DEG at dielectric interfaces, emerging dielectric materials  
Novel oxide-based approaches to engineer SOI and GOI wafers

### **Dielectrics for aggressively scaled CMOS and other field effect devices**

High-k dielectrics on Si  
High-k dielectrics on high mobility semiconductors: Ge, III-V, III-N  
High-k/metal gate stack, characterisation, scaling, stability  
Defect characterisation, engineering of dielectrics, leakage currents  
Electrical characterisation and reliability of devices with alternative dielectrics

### **Dielectrics for memory applications**

High-k dielectrics for MIM (DRAM etc.)  
Resistive switching in dielectrics  
Dielectrics for non-volatile memories (flash, nanocrystal-based memories,...)  
Ferroelectrics

## *Important dates*

<b>Submission of abstracts:</b>	<b>March 31, 2010</b>
<b>Notification of abstracts acceptance:</b>	<b>April 30, 2010</b>
<b>Conference registration (reduced rate):</b>	<b>May 1 - 31, 2010</b>
<b>Accommodation reservation:</b>	<b>May 1 - 31, 2010</b>
<b>Full length paper submission:</b>	<b>June 1, 2010</b>
<b>Conference:</b>	<b>June 28 – 30, 2010</b>

## ***Abstract submission***

Abstract is limited to one page and should be prepared using **template**, downloaded from the **WoDiM 2010** web-site. The abstract will be printed in greyscale. The abstracts should be sent to the conference organizers before **March 31, 2010**. The authors will be notified of abstract acceptance before April 30, 2010.

Abstract should be mailed to [info@wodim2010.sk](mailto:info@wodim2010.sk) as an attachment. The authors are kindly asked to indicate following informations in the e-mail:

- Name of the corresponding author and institution
- Corresponding conference topic
- Preferred form of presentation (oral or poster)

## ***Publications***

**Accepted papers will be published in The Journal of Vacuum Science and Technology B**

## ***Conference Fee***

The conference office kindly requests participating scientists to pay the following fee:

**Before May 31, 2010: 400 €**

**After May 31, 2010: 450 €**

Reduced fee of 300 € is foreseen for PhD students.

A fee of 300 € is requested for accompanying guests not joining the scientific program of WoDiM 2010.

The following conference services are included in the conference fee of participating scientists:

- WoDiM 2010 conference (guest speakers, conference booklet, JVST B publication charge, coffee breaks etc.)
- Lunch & dinner during the Conference
- Social program (conference dinner & excursion)

***We are grateful to the following sponsors of the WoDiM 2010***



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**WoDiM 2010**

will be organized by the Institute of Electrical Engineering, SAS, Bratislava

Conference web-page: <http://www.wodim2010.sk>

